

### **General Description**

The WSF70N10 is the highest performance trench N-Ch MOSFET with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WSF70N10 meet the RoHS and Green Product requirement,100% EAS guaranteed with full function reliability approved.

#### **Features**

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

### **Product Summery**

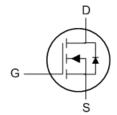
BV <sub>DSS</sub>	R <sub>DSON</sub>	I <sub>D</sub>
100V	10mΩ	70A

### **Applications**

- Power Management in TV Converter.
- DC-DC Converter
- LED TV Back Light

### **TO-252 Pin Configuration**





### **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units	
$V_{DS}$	Drain-Source Voltage	100	V	
$V_{GS}$	Gate-Source Voltage	±25	V	
I <sub>D</sub> @T <sub>C</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	70	Α	
I <sub>D</sub> @T <sub>C</sub> =100℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	35	Α	
I <sub>D</sub> @T <sub>A</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	8.2	Α	
I <sub>D</sub> @T <sub>A</sub> =70°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	6.6	Α	
I <sub>DM</sub>	Pulsed Drain Current <sup>2,</sup> T <sub>C</sub> =25°C	150	Α	
EAS	Avalanche Energy, Single pulse,L=0.5mH	169	mJ	
I <sub>AS</sub>	Avalanche Current, Single pulse,L=0.5mH	26	Α	
P <sub>D</sub> @T <sub>C</sub> =25℃	Total Power Dissipation⁴	113	W	
P <sub>D</sub> @T <sub>C</sub> =100°C	Total Power Dissipation⁴	45	W	
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	℃	
$T_J$	Operating Junction Temperature Range	150	$^{\circ}$	

### **Thermal Data**

Symbol	Parameter		Max.	Unit
$R_{ heta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>		50	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case <sup>1</sup>		1.1	°C/W



### Electrical Characteristics (T<sub>J</sub>=25 C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage V <sub>GS</sub> =0V , I <sub>D</sub> =250uA		100			V	
$\triangle BV_{DSS}/\triangle T_{J}$	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =1mA		0.096		V/°C	
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =30A		10	13	mΩ	
$V_{GS(th)}$	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> . In =250uA	2.0	3.0	4.0	٧	
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	VGS-VDS , ID -250UA		-5.5		mV/℃	
	Drain Source Leakage Current	$V_{DS}$ =80V , $V_{GS}$ =0V , $T_{J}$ =25 $^{\circ}$ C			1		
I <sub>DSS</sub>	Drain-Source Leakage Current	$V_{DS}$ =80V , $V_{GS}$ =0V , $T_{J}$ =55 $^{\circ}$ C			5	uA	
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}$ = $\pm 20V$ , $V_{DS}$ = $0V$			±100	nA	
gfs	Forward Transconductance V <sub>DS</sub> =5V , I <sub>D</sub> =30A			27		S	
$R_g$	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		1.0	1.8	Ω	
$Q_g$	Total Gate Charge (10V)			42			
$Q_{gs}$	Gate-Source Charge	V <sub>DS</sub> =80V , V <sub>GS</sub> =10V , I <sub>D</sub> =30A		12		nC	
$Q_{gd}$	Gate-Drain Charge			12			
T <sub>d(on)</sub>	Turn-On Delay Time			19			
Tr	Rise Time	$V_{DD}$ =50V , $V_{GS}$ =10V , $R_{G}$ =3 $\Omega$ ,		9			
T <sub>d(off)</sub>	Turn-Off Delay Time	I <sub>D</sub> =1A		36		ns	
T <sub>f</sub>	Fall Time			22			
C <sub>iss</sub>	Input Capacitance			2100			
Coss	Output Capacitance	V <sub>DS</sub> =15V , V <sub>GS</sub> =0V , f=1MHz		255		pF	
C <sub>rss</sub>	Reverse Transfer Capacitance			100			

### **Guaranteed Avalanche Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy <sup>5</sup>	V <sub>DD</sub> =25V , L=0.5mH , I <sub>AS</sub> =26A	150			mJ

### **Diode Characteristics**

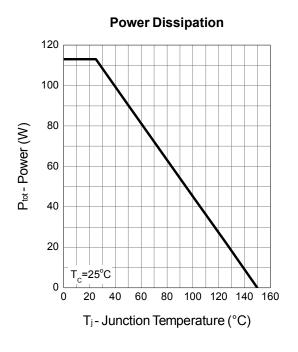
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current <sup>1,6</sup>	V =V =0V Force Current			30	Α
I <sub>SM</sub>	Pulsed Source Current <sup>2,6</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			60	Α
$V_{SD}$	Diode Forward Voltage <sup>2</sup> V <sub>GS</sub> =0V , I <sub>S</sub> =15A , T <sub>J</sub> =25°C				1.3	V
t <sub>rr</sub>	Reverse Recovery Time	I= 450 dI/dt 4000 / T 05°C		42		nS
Qrr	Reverse Recovery Charge	IF=15A,dI/dt=100A/µs,T <sub>J</sub> =25℃		90		nC

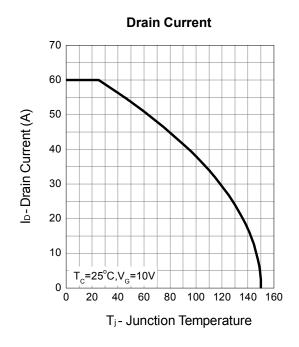
#### Note:

- 1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper,t<10sec.
- 2.The data tested by pulsed , pulse width  $\,\leq\,300\text{us}$  , duty cycle  $\,\leq\,2\%$
- 3. The EAS data shows Max. rating . The test condition is  $V_{DS}$ =25V, $V_{GS}$ =10V,L=0.5mH,I<sub>AS</sub>=26A
- 4.The power dissipation is limited by 150  $^{\circ}\mathrm{C}\,$  junction temperature
- 5. The Min. value is 100% EAS tested guarantee.
- 6.The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub>, in real applications, should be limited by total power dissipation.

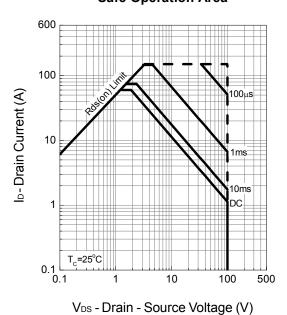


### **Typical Operating Characteristics**

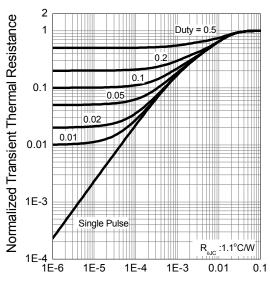




### **Safe Operation Area**



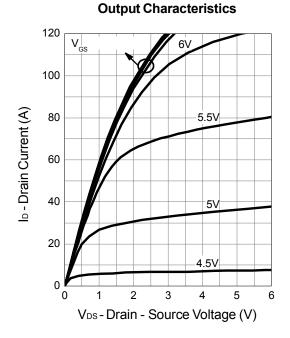
### **Thermal Transient Impedance**



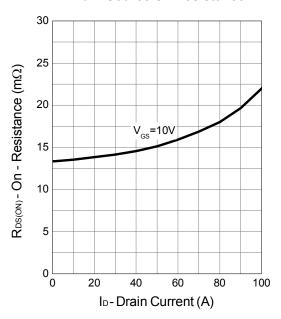
Square Wave Pulse Duration (sec)



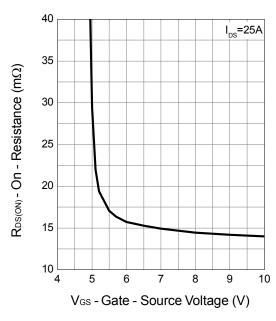
## **Typical Operating Characteristics (Cont.)**



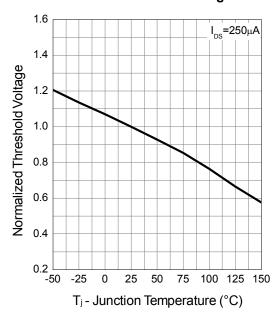
#### **Drain-Source On Resistance**



### **Gate-Source On Resistance**



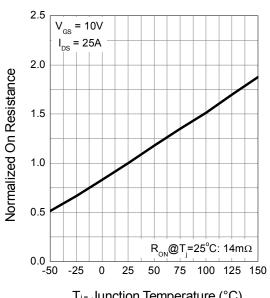
### **Gate Threshold Voltage**



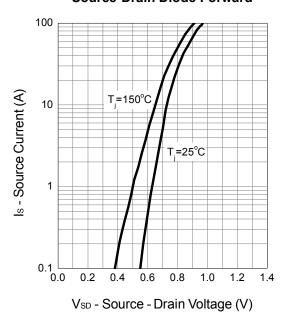


### **Typical Operating Characteristics (Cont.)**

# **Drain-Source On Resistance**

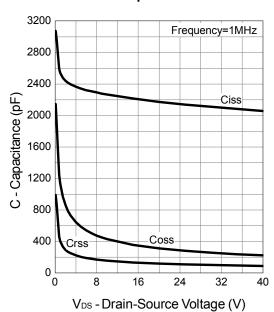


#### Source-Drain Diode Forward

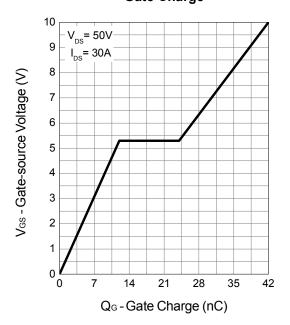


T<sub>j</sub>- Junction Temperature (°C)

### Capacitance

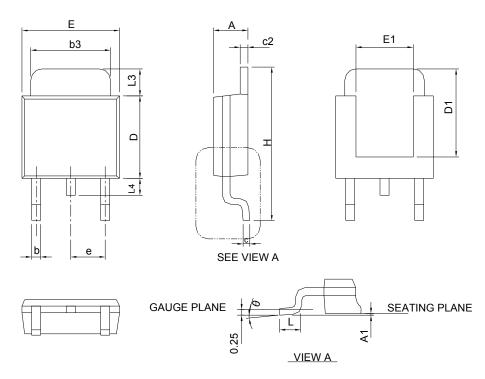


### **Gate Charge**



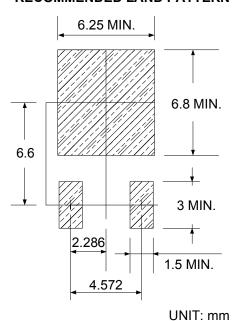


# Package Information: TO-252



Ş	TO-252				
SYZEO_	MILLIM	ETERS	INC	HES	
Ь	MIN.	MAX.	MIN.	MAX.	
Α	2.18	2.39	0.086	0.094	
A1	-	0.13	-	0.005	
b	0.50	0.89	0.020	0.035	
b3	4.95	5.46	0.195	0.215	
С	0.46	0.61	0.018	0.024	
c2	0.46	0.89	0.018	0.035	
D	5.33	6.22	0.210	0.245	
D1	4.57	6.00	0.180	0.236	
Е	6.35	6.73	0.250	0.265	
E1	3.81	6.00	0.150	0.236	
е	2.29 BSC		0.090	) BSC	
Н	9.40	10.41	0.370	0.410	
L	0.90	1.78	0.035	0.070	
L3	0.89	2.03	0.035	0.080	
L4	-	1.02	-	0.040	
θ	0°	8°	0°	8°	

### **RECOMMENDED LAND PATTERN**





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